

INTERNATIONAL STANDARD



**Printed board assemblies –
Part 2: Sectional specification – Requirements for surface mount soldered
assemblies**



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assemblies**

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CONTENTS

FOREWORD.....	5
1 Scope.....	7
2 Normative references	7
3 Terms and definitions	7
4 General requirements	7
5 Surface mounting of components.....	7
5.1 General.....	7
5.2 Alignment requirements	8
5.3 Process control.....	8
5.4 Surface mounted component requirements	8
5.5 Flatpack lead forming.....	8
5.5.1 General	8
5.5.2 Surface mounted device lead bends	8
5.5.3 Surface mounted device lead deformation	9
5.5.4 Flattened leads.....	9
5.5.5 Dual-in-line packages (DIPs)	9
5.5.6 Parts not configured for surface mounting.....	9
5.6 Small devices with two terminations	9
5.6.1 General	9
5.6.2 Stack mounting.....	9
5.6.3 Devices with external deposited elements.....	9
5.7 Lead component body positioning	10
5.7.1 General	10
5.7.2 Axial-leaded components.....	10
5.7.3 Other components	10
5.8 Parts configured for butt lead mounting.....	10
5.9 Non-conductive adhesive coverage limits.....	10
6 Acceptance requirements	10
6.1 General.....	10
6.2 Control and corrective actions.....	10
6.3 Surface soldering of leads and terminations.....	11
6.3.1 General	11
6.3.2 Solder fillet height and heel fillets	11
6.3.3 Flat ribbon L and gull-wing leads	12
6.3.4 Round or flattened (coined) leads	13
6.3.5 J leads.....	14
6.3.6 Rectangular or square end component	15
6.3.7 Cylindrical end-cap terminations	16
6.3.8 Bottom only terminations	17
6.3.9 Castellated terminations	18
6.3.10 Butt joints	19
6.3.11 Inward L-shaped ribbon leads.....	20
6.3.12 Flat lug leads.....	21
6.3.13 Ball grid array.....	22
6.3.14 Column grid array.....	23
6.3.15 Bottom termination components.....	24

6.3.16	Components with bottom thermal plane terminations (D-Pak)	24
6.3.17	P-style terminations	26
6.4	General post-soldering requirements applicable to all surface-mounted assemblies	26
6.4.1	Dewetting	26
6.4.2	Leaching	26
6.4.3	Pits, voids, blowholes, and cavities	26
6.4.4	Solder wicking	27
6.4.5	Solder webs and skins	27
6.4.6	Bridging	27
6.4.7	Degradation of marking	27
6.4.8	Solder spikes	27
6.4.9	Disturbed joint	27
6.4.10	Component damage	27
6.4.11	Open circuit, non-wetting	27
6.4.12	Component tilting	27
6.4.13	Non-conducting adhesive encroachment	28
6.4.14	Open circuit, no solder available	28
6.4.15	Component on edge	28
7	Rework and repair	28
Annex A	(normative) Placement requirements for surface mounted devices	30
A.1	General	30
A.2	Component positioning	30
A.3	Small devices incorporating two terminations	30
A.3.1	Metallization coverage over the land (side-to-side)	30
A.3.2	Metallization coverage over the land (end)	30
A.4	Mounting of cylindrical end-cap devices (MELFs)	30
A.5	Registration of castellated chip carriers	30
A.6	Surface mounted device lead and land contact	30
A.7	Surface mounted device lead side overhang	30
A.8	Surface mounted device lead toe overhang	31
A.9	Surface mounted device lead height off land (prior to soldering)	31
A.10	Positioning of J lead devices	31
A.11	Positioning gull-wing lead devices	31
A.12	External connections to packaging and interconnect structures	31
Bibliography		32
Figure 1	Lead formation for surface mounted device	8
Figure 2	Fillet height	12
Figure 3	Flat ribbon and gull-wing leads	13
Figure 4	Round or flattened (coined) lead joint	14
Figure 5	J lead joint	15
Figure 6	Rectangular or square end components	16
Figure 7	Cylindrical end-cap terminations	17
Figure 8	Bottom only terminations	18
Figure 9	Leadless chip carriers with castellated terminations	19
Figure 10	Butt joints	20

Figure 11 – Inward L-shaped ribbon leads	21
Figure 12 – Flat lug leads	22
Figure 13 – BGA with collapsing balls	23
Figure 14 – Bottom termination components	24
Figure 15 – Bottom thermal plane terminations	25
Figure 16 – P-style terminations	26
Table 1 – BGA with non-collapsing balls	23
Table 2 – Column grid array.....	23
Table 3 – Reworkable defects	29

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PRINTED BOARD ASSEMBLIES –**Part 2: Sectional specification –
Requirements for surface mount soldered assemblies****FOREWORD**

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International Standard IEC 61191-2 has been prepared by IEC technical committee 91: Electronics assembly technology.

This third edition cancels and replaces the second edition published in 2013. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) the requirements have been updated to be compliant with the acceptance criteria in IPC-A-610F;
- b) some of the terminology used in the document has been updated;
- c) references to IEC standards have been corrected;
- d) five termination styles have been added.

The text of this International Standard is based on the following documents:

CDV	Report on voting
91/1386/CDV	91/1429/RVC

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts of IEC 61191 under the general title *Printed board assemblies* can be found in the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

- reconfirmed,
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- replaced by a revised edition, or
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PRINTED BOARD ASSEMBLIES –

Part 2: Sectional specification – Requirements for surface mount soldered assemblies

1 Scope

This part of IEC 61191 gives the requirements for surface mount solder connections. The requirements pertain to those assemblies that are totally surface mounted or to the surface mounted portions of those assemblies that include other related technologies (e.g. through-hole, chip mounting, terminal mounting, etc.).

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60194, *Printed board design, manufacture and assembly – Terms and definitions*

IEC 61191-1, *Printed board assemblies – Part 1: Generic specification – Requirements for soldered electrical and electronic assemblies using surface mount and related assembly technologies*

IPC-A-610, *Acceptability of Electronic Assemblies*

3 Terms and definitions

For the purposes of this document, the terms and definitions given in IEC 60194 apply.

ISO and IEC maintain terminological databases for use in standardization at the following addresses:

- IEC Electropedia: available at <http://www.electropedia.org/>
- ISO Online browsing platform: available at <http://www.iso.org/obp>

4 General requirements

The requirements of IEC 61191-1 are a mandatory part of this specification.

Workmanship shall meet the requirements of IPC-A-610 in accordance with the classification requirements of this document.

5 Surface mounting of components

5.1 General

This clause covers assembly of components that are placed on the surface to be manually or machine soldered and includes components designed for surface mounting as well as through-hole components that have been adapted for surface mounting technology.